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## ABSTRACT OF THE DISCLOSURE

A method of fabricating a micromechanical device. Several of the micromechanical devices are fabricated 20 on a common wafer. After the devices are fabricated, the sacrificial layers are removed 22 leaving open spaces where the sacrificial layers once were. These open 5 spaces allow for movement of the components of the micromechanical device. The devices optionally are passivated 24, which may include the application of a lubricant. After the devices have been passivated, they are tested 26 in wafer form. After testing 26, any surface treatments that are not compatible with the remainder of the processing steps are removed 28. The substrate wafer containing the completed devices receives a conformal overcoat 30. The overcoat layer is 10 thick enough to project the micromechanical structures, but thin and light enough to prevent deforming the underlying micromechanical structures. Once the devices on the wafer are overcoated, the wafer is separated 32, and the known good devices are cleaned 34 to remove debris left by the dicing process. Once the devices are separated and cleaned, the overcoat may be removed, however, the overcoat typically is left in place to protect the device during the 15 initial stages of the packaging process. Typically the devices are mounted 36 in the package substrate, the overcoat removed 38 from the devices, and the package containing the micromechanical device finished by sealing the package to enclose the device.